

ELECTRONICALLY FILED ON 25 August 2006

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Marcos Karnezos	Attorney Docket No.: CPAC 1017-5 D3
Application No.: 10/632,552	Examiner: Chris C. Chu
Filed: 02 August 2003	Group: 2815
Title: Semiconductor Multi-Package Module Having Package Stacked Over Die-Up Flip Chip Ball Grid Array Package And Having Wire Bond Interconnect Between Stacked Packages	Confirmation No.: 2572
	Customer No. 22470

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

It is requested that the information identified in this statement be considered by the Examiner and made of record in the above-identified application. This statement is not intended to represent that a search has been made or that the information cited in the statement is, or is considered to be, material to patentability as defined in 37 C.F.R. 1.56.

Enclosed with this statement is a Form PTO/SB/08A. The Examiner is requested to initial the form and return it to the undersigned in accordance with M.P.E.P. 609.

Also enclosed with this statement is a copy of each cited document as required by 37 C.F.R. 1.98. However, since this application was filed after June 30, 2003, copies of U. S. Patents and U. S. Patent Application Publications are not enclosed. (See O. G. Notice of August 5, 2003.)

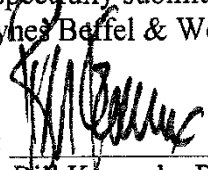
This statement should be considered under 37 C.F.R. 1.97(e) because it is being filed before the mailing date of a FINAL office action, a Notice of Allowance, or an action that otherwise closes prosecution in the subject application, whichever occurs first, AND it is accompanied by the \$180 fee set forth in 37 C.F.R. 1.17(p).

Fee Authorization. The Commissioner is hereby authorized to charge any additional fees or credit any overpayment associated with this communication to Deposit Account No. 50-0869 (CPAC 1017-5 D3).

Respectfully submitted,
Haynes Beffel & Wolfeld LLP

Date: 25 August 2006

By:

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**INFORMATION DISCLOSURE STATEMENT
BY APPLICANT**

Substitute for form PTO-1449

Sheet 1 of 1

Application Number	10/632,552
Filing Date	02 August 2003
First Named Inventor	Marcos Karnezos
Art Unit	2815
Examiner Name	Chris C. Chu
Attorney Docket Number	CPAC 1017-5

U.S. PATENT DOCUMENTS

Examiner's Initials		Patent No. Number-Kind Code	Pub. Date MM-DD- YYYY	Name	Pages, Cols, Lines of Relevant Passages or Figures
		US 5,229,960	07-20-1993	De Givry	
		US 5,898,219	04-27-1999	Barrow	
		US 5,899,705	05-04-1999	Akram	
		US 6,118,176	09-12-2000	Tao et al.	
		US 6,133,626	10-17-2000	Hawke et al.	
		US 6,492,726	12-10-2002	Quek et al.	
		US 6,552,423	04-22-2003	Song et al.	
		US 6,706,557	03-16-2004	Koopmans	
		US 6,794,749	09-21-2004	Akram	
		US 6,828,665	12-07-2004	Pu et al.	
		US 6,882,057	04-19-2005	Hsu	
		US 6,900,528	05-31-2006	Mess et al.	
		US 7,053,477	05-30-2006	Karnezos	
		US 2003/0113952	06-19-2003	Sambasivam et al.	
		US 2003/0153134	08-14-2003	Kawata et al.	
		US			
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		US			

FOREIGN PATENT DOCUMENTS

Examiner's Initials		Patent No. Number-Kind Code	Pub. Date MM-DD-YYYY	Name	Pages, Cols, Lines of Relevant Material	T
	B1					
	B2					
	B3					
	B3					
	B4					

**Examiner
Signature****Date
Considered**